

ULTRALOW CAPACITANCE TVS DIODE ARRAY

Features

- Ultra low capacitance: 0.2pF typical
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Up to 4 lines protects
- Leadless flow-through package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: $\pm 30\text{kV}$
Contact discharge: $\pm 30\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 5A (8/20 μs)
- RoHS Compliant

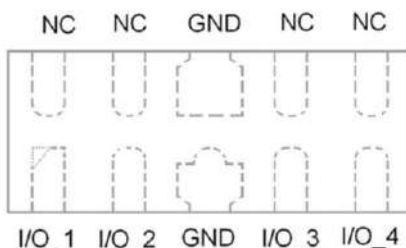
Applications

- HDMI1.3 /1.4/2.0, USB 2.0/3.0/3.1 Type C
- Monitors and flat panel displays
- Set-top box and Digital TV
- MDDI ports
- Video graphics cards
- Digital Video Interface (DVI)
- Notebook Computers
- PCI Express and Serial SATA Ports

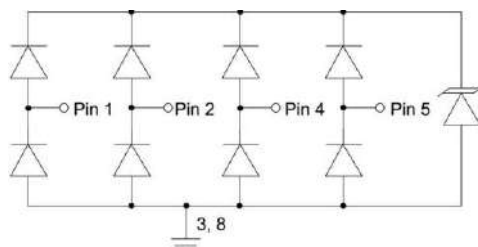
Mechanical Characteristics

- Package: DFN2510-10 (2.5 $\times$ 1.0 $\times$ 0.5mm)
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel:3,000pcs
- Reel Size:7 inch
- Device Marking: 0524B

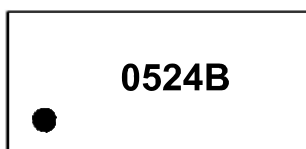
Dimensions DFN2510P10



Pin Configuration



Marking Information



0524B = Device Marking Code
 Dot denotes Pin1

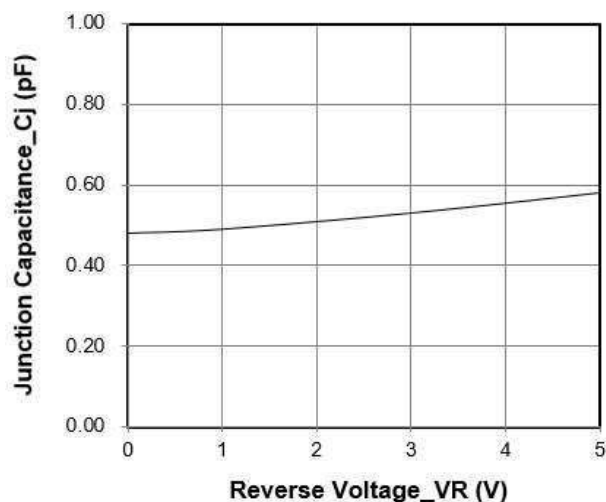
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	Ppk	60	W
Peak Pulse Current (8/20 μs)	I _{PP}	5	A
ESD per IEC 61000-4-2 (Air)	VESD	± 30	kV
ESD per IEC 61000-4-2 (Contact)		± 30	
Operating Temperature Range	T _J	-55 to +125	$^\circ\text{C}$
Storage Temperature Range	T _{stg}	-55 to +150	$^\circ\text{C}$

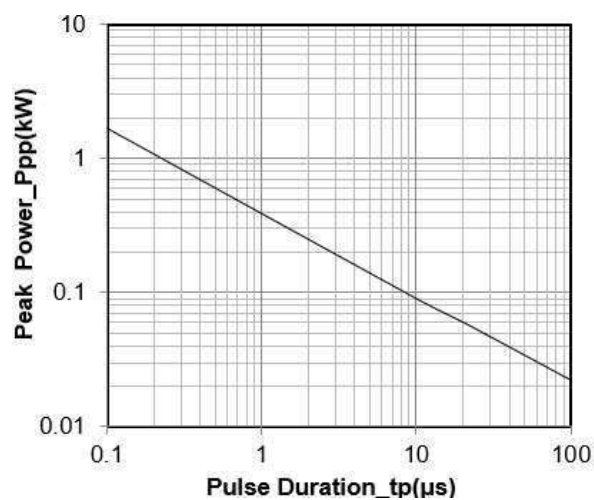
Electrical Characteristics (T_A=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	VRWM	Any I/O pin to ground			5	V
Breakdown Voltage	VBR	IT = 1mA, any I/O pin to ground	6			V
Reverse Leakage Current	IR	VRWM = 5V, any I/O pin to ground			0.2	μA
Clamping Voltage	VC	I _{PP} = 1A (8 x 20μs pulse), any I/O pin to ground		8	9	V
Clamping Voltage	VC	I _{PP} = 5A (8 x 20μs pulse), any I/O pin to ground		9.5	11	V
Junction Capacitance	CJ	VR = 0V, f = 1MHz, between I/O pins		0.2	0.4	pF
Junction Capacitance	CJ	= 0V, f = 1MHz, any I/O pin to ground		0.45	0.65	pF

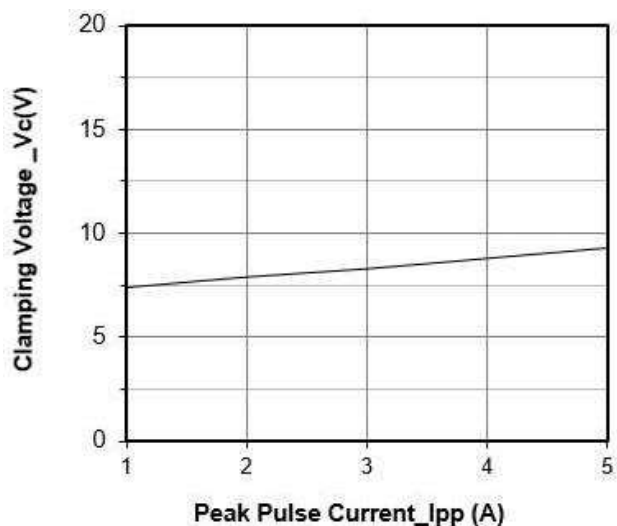
Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)



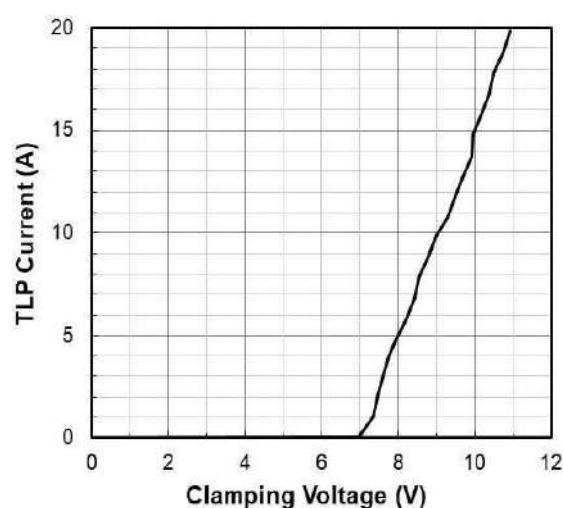
Junction Capacitance vs. Reverse Voltage



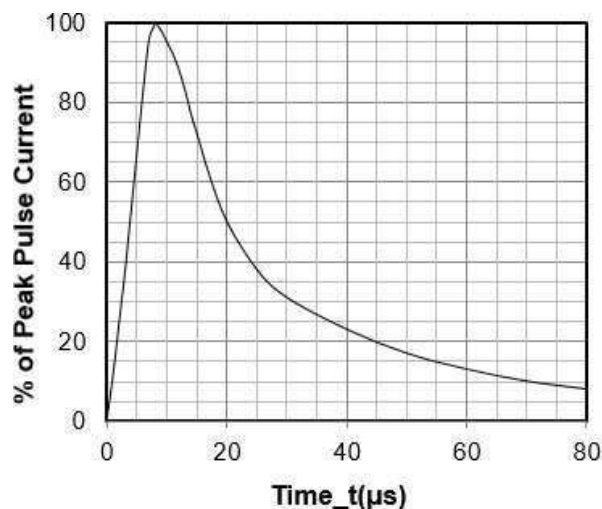
Peak Pulse Power vs. Pulse Time



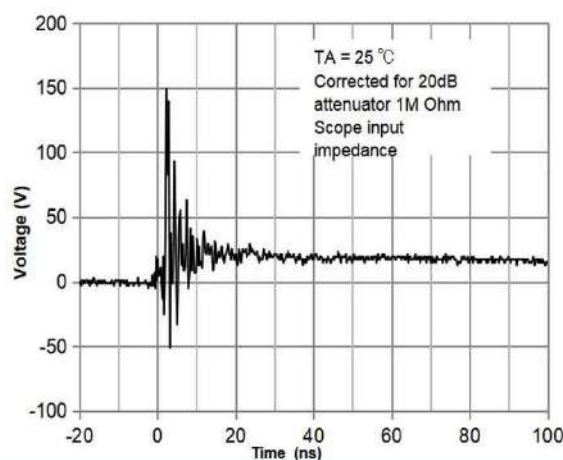
Clamping Voltage vs. Peak Pulse Current



TLP Measurement

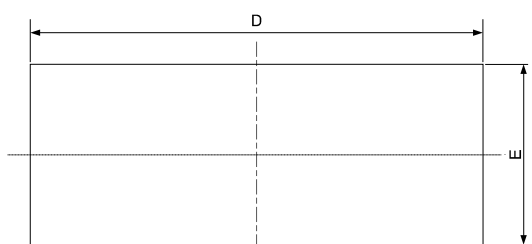


8 X 20μs Pulse Waveform

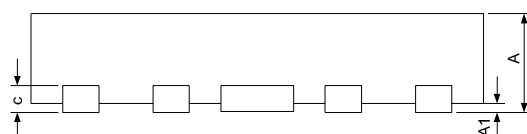


**Note: Data is taken with a 10x attenuator
 ESD Clamping Voltage
 8 kV Contact per IEC61000-4-2**

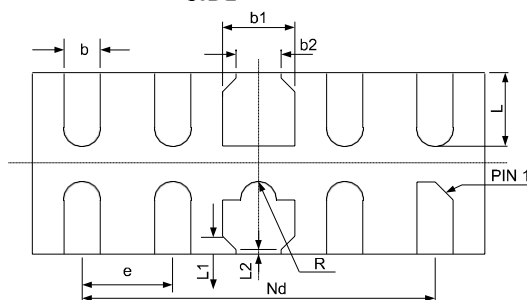
DFN2510-10 Package Outline Drawing



TOP VIEW



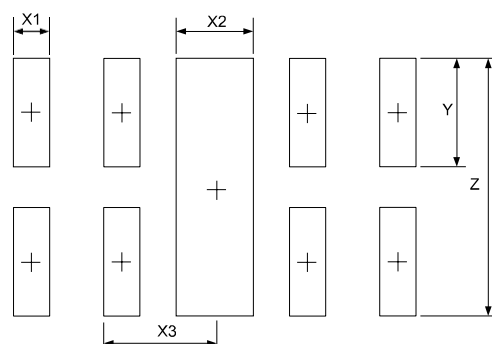
SIDE VIEW



BOTTOM VIEW

SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	M N	NOM	MAX	M N	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.15	0.20	0.25	0.006	0.008	0.010
b1	0.35	0.40	0.45	0.014	0.016	0.018
b2	0.20	0.25	0.30	0.008	0.010	0.012
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.45	2.50	2.55	0.098	0.100	0.102
e	0.50BSC			0.020BSC		
Nd	2.00BSC			0.080BSC		
E	0.95	1.00	1.05	0.038	0.040	0.042
L	0.35	0.40	0.45	0.014	0.016	0.018
L1	0.075REF			0.003REF		
L2	0.050REF			0.002REF		
h	0.08	0.12	0.15	0.003	0.005	0.006
R	0.05	0.10	0.15	0.002	0.004	0.006

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
X1	0.200	0.008
X2	0.400	0.016
X3	0.600	0.024
Y	0.600	0.024
Z	1.400	0.056